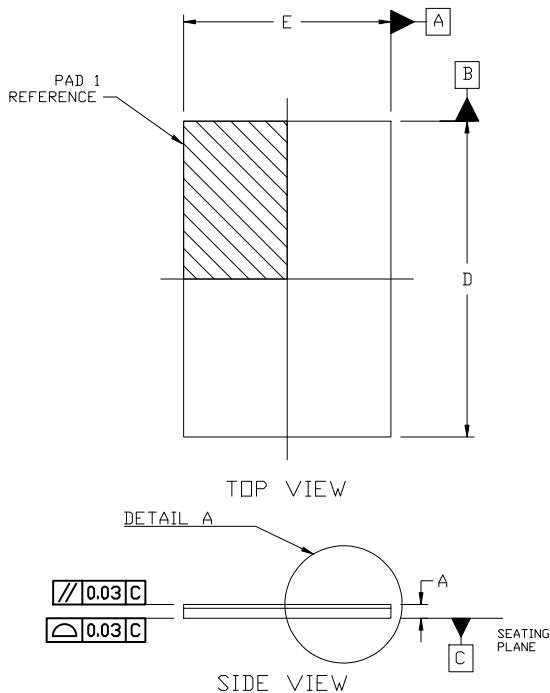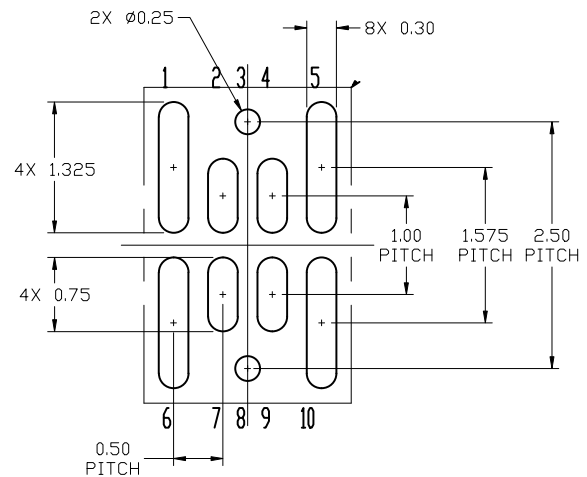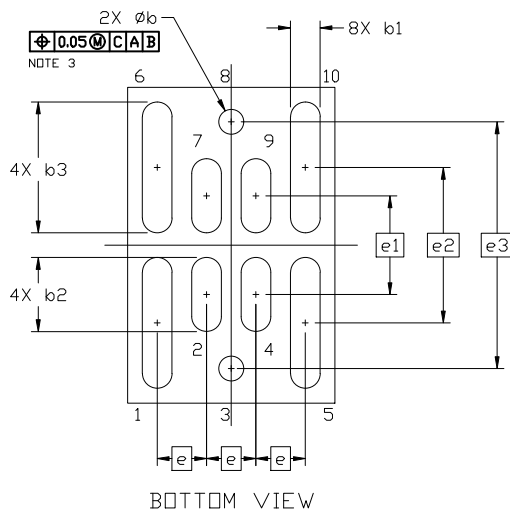**WLCSP10 3.2x2.1x0.14**
CASE 567XT
ISSUE O

DATE 02 APR 2019

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. POSITIONAL TOLERANCE APPLIES TO ALL PADS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.11	0.14	0.17
A3	0.04 REF		
b	0.22	0.25	0.28
b1	0.27	0.30	0.33
b2	0.72	0.75	0.78
b3	1.295	1.325	1.355
D	3.17	3.20	3.23
E	2.07	2.10	2.13
e	0.50 BSC		
e1	1.0 BSC		
e2	1.575 BSC		
e3	2.50 BSC		

PAD 1 REFERENCE

E

A

B

D

TOP VIEW

BACKSIDE COATING

A3

DETAIL A

DETAIL A

// | 0.03 | C

◻ | 0.03 | C

A

C

SEATING PLANE

SIDE VIEW

2X Ø b

⊕ | 0.05 Ⓜ | C | A | B

NOTE 3

8X b1

6   8   10

7   9

4X b3

e1 e2 e3

4X b2

2   4

1   3   5

e e e

BOTTOM VIEW

2X Ø0.25

8X 0.30

1 2 3 4 5

4X 1.325

1.00 1.575 2.50
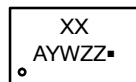PITCH PITCH PITCH

4X 0.75

6 7 8 9 10

0.50 PITCH

RECOMMENDED MOUNTING FOOTPRINT*

∗ For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

GENERIC MARKING DIAGRAM*

XX
AYWZZ▪
○

XX = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
ZZ = Assembly Lot Code
▪ = Pb-Free Package

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DESCRIPTION:	**WLCSP10 3.2x2.1x0.14**		**PAGE 1 OF 1**